Renesas Electronics America Inc - R5F212A7SNFA#V2 Datasheet

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	55
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2.5K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212a7snfa-v2

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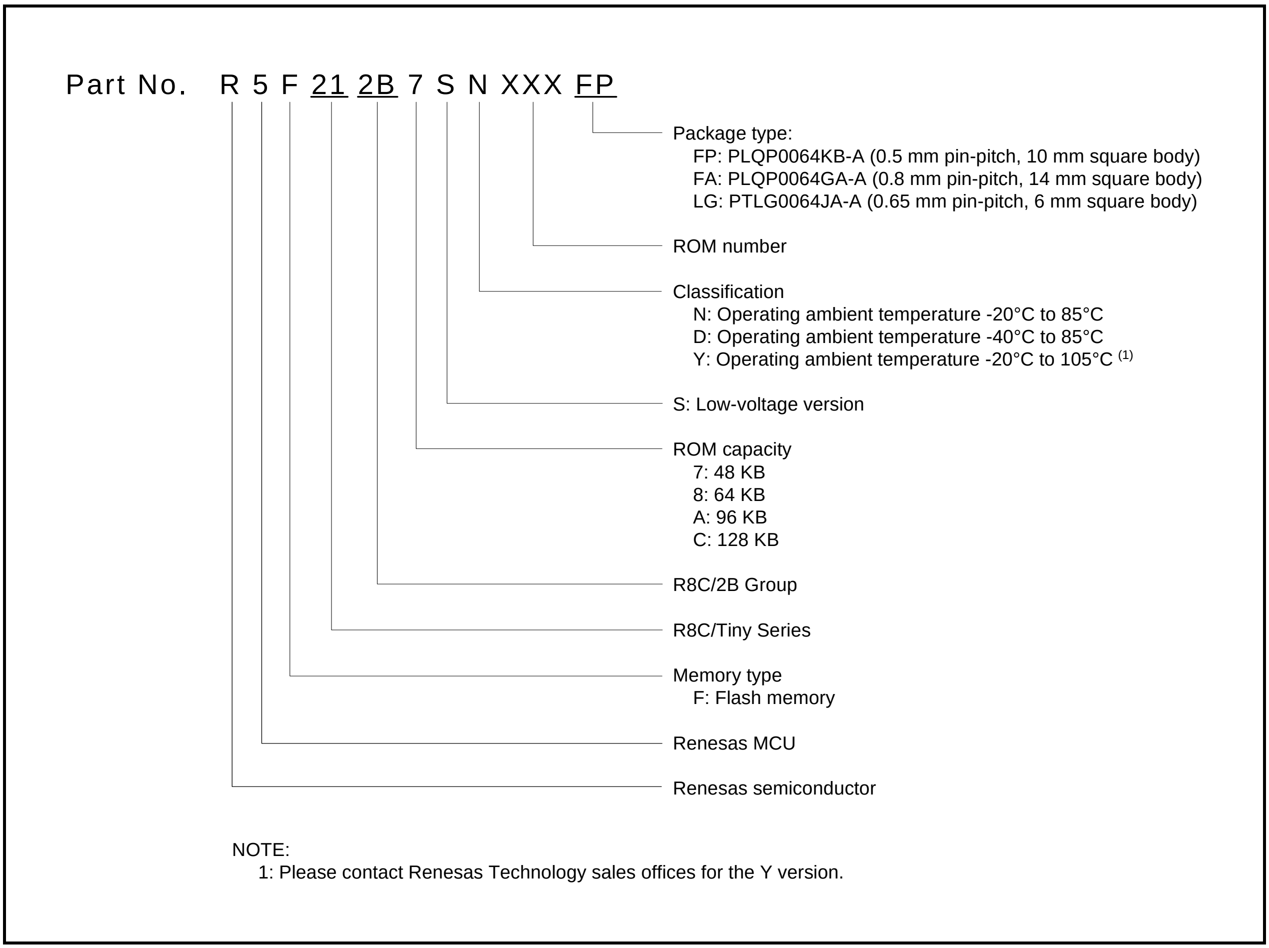
Table 1.2 Specifications for R8C/2A Group (2)

Item	Function	Specification
Serial Interface	UART0, UART1, UART2	Clock synchronous serial I/O/UART × 3
Clock Synchronous Serial I/O with Chip Select (SSU)		1 (shared with I^2C-bus)
I^2C bus(1)		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function
D/A Converter		8-bit resolution × 2 circuits
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 100 times • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 3.0 to 5.5 V) f(XIN) = 10 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 2.2 to 5.5 V)
Current consumption		12 mA (VCC = 5.0 V, f(XIN) = 20 MHz) 5.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) 2.1 µA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) 0.65 µA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version)(2) -20 to 105°C (Y version)(3)
Package		64-pin LQFP • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin FLGA • Package code: PTLG0064JA-A (previous code: 64F0G)

NOTES:
1. I^2C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Specify the D version if D version functions are to be used.
3. Please contact Renesas Technology sales offices for the Y version.

Table 1.3 Specifications for R8C/2B Group (1)

Item	Function	Specification
CPU	Central processing unit	R8C/Tiny series core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns (f(XIN) = 20 MHz, VCC = 3.0 to 5.5 V) 100 ns (f(XIN) = 10 MHz, VCC = 2.7 to 5.5 V) 200 ns (f(XIN) = 5 MHz, VCC = 2.2 to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operation mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM	Refer to **Table 1.6 Product List for R8C/2B Group**.
Power Supply Voltage Detection	Voltage detection circuit	• Power-on reset • Voltage detection 2
I/O Ports	Programmable I/O ports	• Input-only: 2 pins • CMOS I/O ports: 55, selectable pull-up resistor • High current drive ports: 8
Clock	Clock generation circuits	3 circuits: XIN clock oscillation circuit (with on-chip feedback resistor), On-chip oscillator (high-speed, low-speed) (high-speed on-chip oscillator has a frequency adjustment function), XCIN clock oscillation circuit (32 kHz) • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16 • Low power consumption modes: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
		Real-time clock (timer RE)
Interrupts		• External: 5 sources, Internal: 23 sources, Software: 4 sources • Priority levels: 7 levels
Watchdog Timer		15 bits × 1 (with prescaler), reset start selectable
Timer	Timer RA	8 bits × 1 (with 8-bit prescaler) Timer mode (period timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB	8 bits × 1 (with 8-bit prescaler) Timer mode (period timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timer RC	16 bits × 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 3 pins), PWM2 mode (PWM output pin)
	Timer RD	16 bits × 2 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 6 pins), reset synchronous PWM mode (output three-phase waveforms (6 pins), sawtooth wave modulation), complementary PWM mode (output three-phase waveforms (6 pins), triangular wave modulation), PWM3 mode (PWM output 2 pins with fixed period)
	Timer RE	8 bits × 1 Real-time clock mode (count seconds, minutes, hours, days of week), output compare mode
	Timer RF	16 bits × 1 (with capture/compare register pin and compare register pin) Input capture mode, output compare mode



Part No. R 5 F 21 2B 7 S N XXX FP

Package type:
  FP: PLQP0064KB-A (0.5 mm pin-pitch, 10 mm square body)
  FA: PLQP0064GA-A (0.8 mm pin-pitch, 14 mm square body)
  LG: PTLG0064JA-A (0.65 mm pin-pitch, 6 mm square body)

ROM number

Classification
  N: Operating ambient temperature -20°C to 85°C
  D: Operating ambient temperature -40°C to 85°C
  Y: Operating ambient temperature -20°C to 105°C (1)

S: Low-voltage version

ROM capacity
  7: 48 KB
  8: 64 KB
  A: 96 KB
  C: 128 KB

R8C/2B Group

R8C/Tiny Series

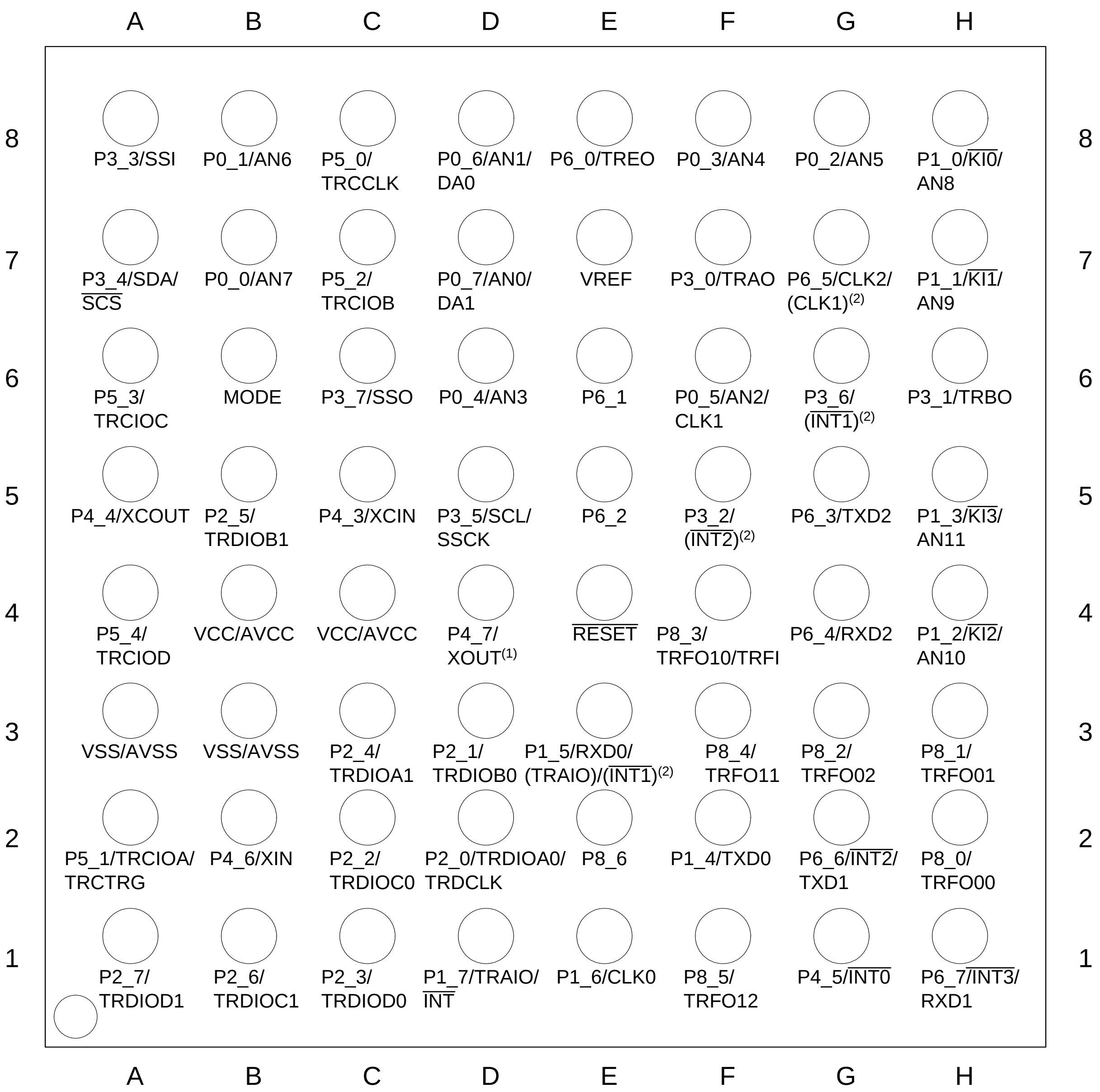
Memory type
  F: Flash memory

Renesas MCU

Renesas semiconductor

NOTE:
1: Please contact Renesas Technology sales offices for the Y version.

Figure 1.2 Part Number, Memory Size, and Package of R8C/2B Group



	A	B	C	D	E	F	G	H
8	P3_3/SSI	P0_1/AN6	P5_0/TRCCLK	P0_6/AN1/DA0	P6_0/TREO	P0_3/AN4	P0_2/AN5	P1_0/$\overline{\mathrm{KI0}}$/AN8
7	P3_4/SDA/$\overline{\mathrm{SCS}}$	P0_0/AN7	P5_2/TRCIOB	P0_7/AN0/DA1	VREF	P3_0/TRAO	P6_5/CLK2/(CLK1)(2)	P1_1/$\overline{\mathrm{KI1}}$/AN9
6	P5_3/TRCIOC	MODE	P3_7/SSO	P0_4/AN3	P6_1	P0_5/AN2/CLK1	P3_6/($\overline{\mathrm{INT1}}$)(2)	P3_1/TRBO
5	P4_4/XCOUT	P2_5/TRDIOB1	P4_3/XCIN	P3_5/SCL/SSCK	P6_2	P3_2/($\overline{\mathrm{INT2}}$)(2)	P6_3/TXD2	P1_3/$\overline{\mathrm{KI3}}$/AN11
4	P5_4/TRCIOD	VCC/AVCC	VCC/AVCC	P4_7/XOUT(1)	$\overline{\mathrm{RESET}}$	P8_3/TRFO10/TRFI	P6_4/RXD2	P1_2/$\overline{\mathrm{KI2}}$/AN10
3	VSS/AVSS	VSS/AVSS	P2_4/TRDIOA1	P2_1/TRDIOB0	P1_5/RXD0/(TRAIO)/($\overline{\mathrm{INT1}}$)(2)	P8_4/TRFO11	P8_2/TRFO02	P8_1/TRFO01
2	P5_1/TRCIOA/TRCTRG	P4_6/XIN	P2_2/TRDIOC0	P2_0/TRDIOA0/TRDCLK	P8_6	P1_4/TXD0	P6_6/$\overline{\mathrm{INT2}}$/TXD1	P8_0/TRFO00
1	P2_7/TRDIOD1	P2_6/TRDIOC1	P2_3/TRDIOD0	P1_7/TRAIO/$\overline{\mathrm{INT}}$	P1_6/CLK0	P8_5/TRFO12	P4_5/$\overline{\mathrm{INT0}}$	P6_7/$\overline{\mathrm{INT3}}$/RXD1

Package: PTLG0064JA-A (64F0G)

NOTES:
1. P4_7 is an input-only port.
2. Can be assigned to the pin in parentheses by a program.

Pin assignments (top view)

Figure 1.5 **64-pin FLGA Package Pin Assignment (Top Perspective View)**

Table 1.7 Pin Name Information by Pin Number (1)

Pin Number	Control Pin	Port	I/O Pin Functions for of Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I^{2}C bus	A/D Converter, D/A Converter
1		P3_3				SSI		
2		P3_4				SCS	SDA	
3	MODE							
4	XCIN	P4_3						
5	XCOUT	P4_4						
6	$\overline{\text{RESET}}$							
7	XOUT	P4_7						
8	VSS/AVSS							
9	XIN	P4_6						
10	VCC/AVCC							
11		P5_4		TRCIOD				
12		P5_3		TRCIOC				
13		P5_2		TRCIOB				
14		P5_1		TRCIOA/TRCTRG				
15		P5_0		TRCCLK				
16		P2_7		TRDIOD1				
17		P2_6		TRDIOC1				
18		P2_5		TRDIOB1				
19		P2_4		TRDIOA1				
20		P2_3		TRDIOD0				
21		P2_2		TRDIOC0				
22		P2_1		TRDIOB0				
23		P2_0		TRDIOA0/TRDCLK				
24		P1_7	$\overline{\text{INT1}}$	TRAIO				
25		P1_6			CLK0			
26		P1_5	($\overline{\text{INT1}}$)(1)	(TRAIO)(1)	RXD0			
27		P1_4			TXD0			
28		P8_6						
29		P8_5		TRFO12				
30		P8_4		TRFO11				
31		P8_3		TRFO10/TRFI				
32		P8_2		TRFO02				
33		P8_1		TRFO01				
34		P8_0		TRFO00				
35		P6_0		TREO				
36		P4_5	$\overline{\text{INT0}}$	$\overline{\text{INT0}}$				
37		P6_6	$\overline{\text{INT2}}$		TXD1			
38		P6_7	$\overline{\text{INT3}}$		RXD1			
39		P6_5			(CLK1)(1)/ CLK2			
40		P6_4			RXD2			
41		P6_3			TXD2			
42		P3_1		TRBO				
43		P3_0		TRAO				
44		P3_6	($\overline{\text{INT1}}$)(1)					
45		P3_2	($\overline{\text{INT2}}$)(1)					

NOTE:

1. Can be assigned to the pin in parentheses by a program.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.
Interrupt are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.
The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has higher priority than IPL, the interrupt is enabled.

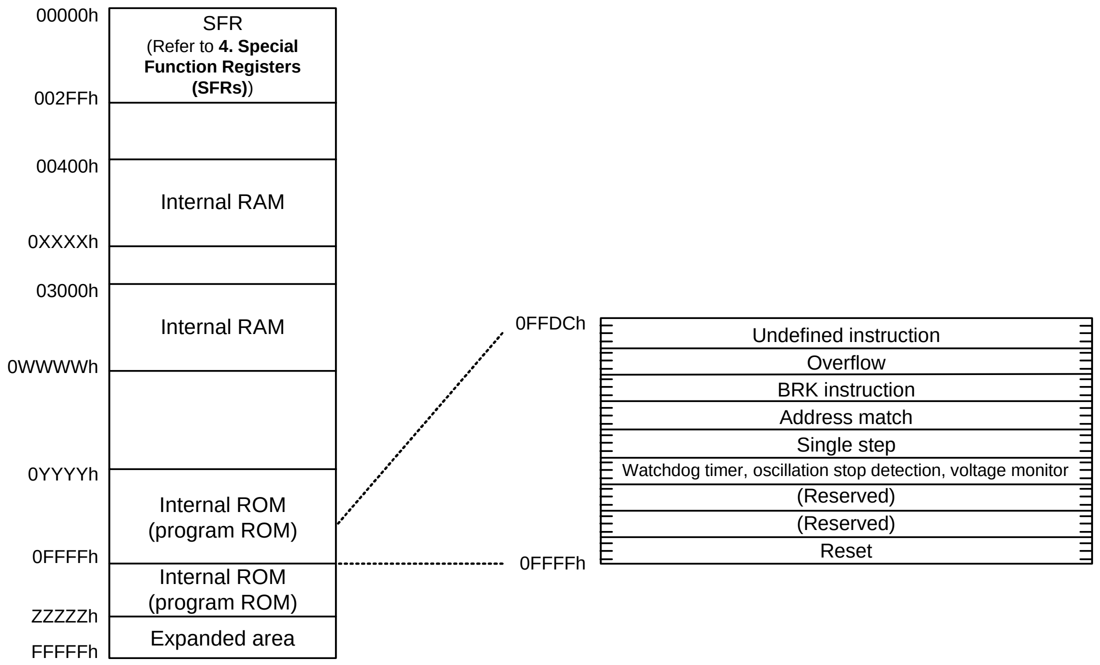
2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3. Memory

3.1 R8C/2A Group

Figure 3.1 is a Memory Map of R8C/2A Group. The R8C/2A group has 1 Mbyte of address space from addresses 00000h to FFFFFh.
The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.



NOTE:
1. The blank regions are reserved. Do not access locations in these regions.

Internal ROM			Internal RAM		
Size	Address 0YYYYh	Address ZZZZZh	Size	Address 0XXXXh	Address 0WWWWh
48 Kbytes	04000h	–	2.5 Kbytes	00DFFh	–
64 Kbytes	04000h	13FFFh	3 Kbytes	00FFFh	–
96 Kbytes	04000h	1BFFFh	7 Kbytes	011FFh	03DFFh
128 Kbytes	04000h	23FFFh	7.5 Kbytes	011FFh	03FFFh

Figure 3.1 Memory Map of R8C/2A Group

Table 4.2 SFR Information (2)(1)

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
004Ch	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh			
004Fh	SSU/IIC Interrupt Control Register(2)	SSUIC / IICIC	XXXXX000b
0050h	Compare 1 Interrupt Control Register	CMP1IC	XXXXX000b
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh	Timer RF Interrupt Control Register	TRFIC	XXXXX000b
005Ch	Compare 0 Interrupt Control Register	CMP0IC	XXXXX000b
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
005Fh	Capture Interrupt Control Register	CAPIC	XXXXX000b
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 4.5 SFR Information (5)(1)

Address	Register	Symbol	After reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0102h	Timer RA Mode Register	TRAMR	00h
0103h	Timer RA Prescaler Register	TRAPRE	FFh
0104h	Timer RA Register	TRA	FFh
0105h	LIN Control Register 2	LINCR2	00h
0106h	LIN Control Register	LINCR	00h
0107h	LIN Status Register	LINST	00h
0108h	Timer RB Control Register	TRBCR	00h
0109h	Timer RB One-Shot Control Register	TRBOCR	00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRE	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary Register	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h	Timer RE Second Data Register / Counter Data Register	TRESEC	00h
0119h	Timer RE Minute Data Register / Compare Data Register	TREMIN	00h
011Ah	Timer RE Hour Data Register	TREHR	00h
011Bh	Timer RE Day of Week Data Register	TREWK	00h
011Ch	Timer RE Control Register 1	TRECR1	00h
011Dh	Timer RE Control Register 2	TRECR2	00h
011Eh	Timer RE Clock Source Select Register	TRECSR	00001000b
011Fh			
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0127h			00h
0128h	Timer RC General Register A	TRCGRA	FFh
0129h			FFh
012Ah	Timer RC General Register B	TRCGRB	FFh
012Bh			FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh			FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh			FFh
0130h	Timer RC Control Register 2	TRCCR2	00011111b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h			
0134h			
0135h			
0136h			
0137h	Timer RD Start Register	TRDSTR	11111100b
0138h	Timer RD Mode Register	TRDMR	00001110b
0139h	Timer RD PWM Mode Register	TRDPMR	10001000b
013Ah	Timer RD Function Control Register	TRDFCR	10000000b
013Bh	Timer RD Output Master Enable Register 1	TRDOER1	FFh
013Ch	Timer RD Output Master Enable Register 2	TRDOER2	01111111b
013Dh	Timer RD Output Control Register	TRDOCR	00h
013Eh	Timer RD Digital Filter Function Select Register 0	TRDDF0	00h
013Fh	Timer RD Digital Filter Function Select Register 1	TRDDF1	00h

NOTE:

1. The blank regions are reserved. Do not access locations in these regions

5. Electrical Characteristics

The electrical characteristics of N version (Topr = –20°C to 85°C) and D version (Topr = –40°C to 85°C) are listed below.
Please contact Renesas Technology sales offices for the electrical characteristics in the Y version (Topr = –20°C to 105°C).

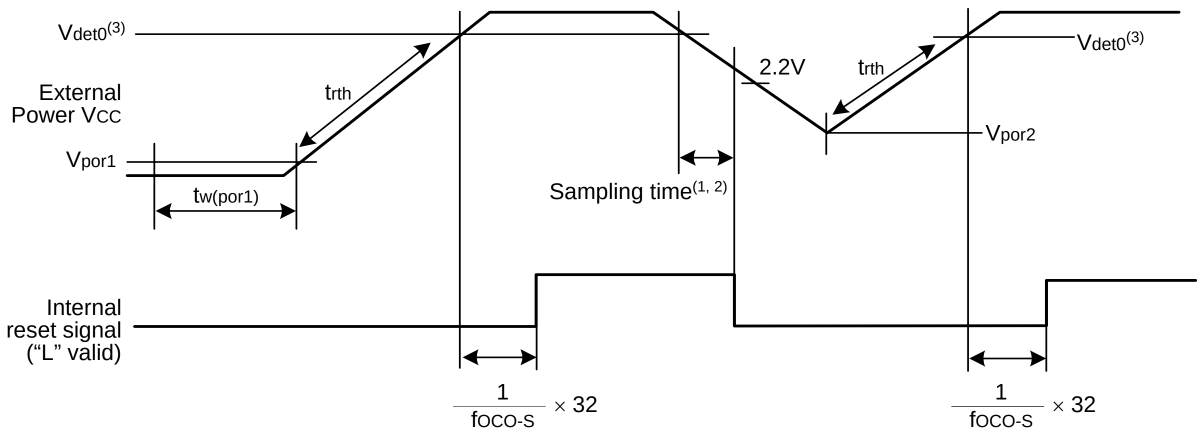
Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage		-0.3 to 6.5	V
V_I	Input voltage		-0.3 to V_{CC} + 0.3	V
V_O	Output voltage		-0.3 to V_{CC} + 0.3	V
P_d	Power dissipation	T_{opr} = 25°C	700	mW
T_{opr}	Operating ambient temperature		-20 to 85 (N version) / -40 to 85 (D version)	°C
T_{stg}	Storage temperature		-65 to 150	°C

Table 5.10 Power-on Reset Circuit, Voltage Monitor 0 Reset Electrical Characteristics(3)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por1}	Power-on reset valid voltage(4)		–	–	0.1	V
V_{por2}	Power-on reset or voltage monitor 0 reset valid voltage		0	–	V_{det0}	V
t_{rth}	External power V_{CC} rise gradient(2)		20	–	–	mV/msec

NOTES:
1. The measurement condition is T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. This condition (external power VCC rise gradient) does not apply if $V_{CC} \geq 1.0$ V.
3. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVD0ON bit in the OFS register to 0, the VW0C0 and VW0C6 bits in the VW0C register to 1 respectively, and the VCA25 bit in the VCA2 register to 1.
4. $t_{w(por1)}$ indicates the duration the external power V_{CC} must be held below the effective voltage (V_{por1}) to enable a power on reset. When turning on the power for the first time, maintain $t_{w(por1)}$ for 30 s or more if $-20°C \leq T_{opr} \leq 85°C$, maintain $t_{w(por1)}$ for 3,000 s or more if $-40°C \leq T_{opr} < -20°C$.



NOTES:
1. When using the voltage monitor 0 digital filter, ensure that the voltage is within the MCU operation voltage range (2.2 V or above) during the sampling time.
2. The sampling clock can be selected. Refer to **6. Voltage Detection Circuit** of Hardware Manual for details.
3. V_{det0} indicates the voltage detection level of the voltage detection 0 circuit. Refer to **6. Voltage Detection Circuit** of Hardware Manual for details.

Figure 5.3 Power-on Reset Circuit Electrical Characteristics

Table 5.14 Timing Requirements of Clock Synchronous Serial I/O with Chip Select(1)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time			4	–	–	t_{CYC}(2)
t_{HI}	SSCK clock "H" width			0.4	–	0.6	t_{SUCYC}
t_{LO}	SSCK clock "L" width			0.4	–	0.6	t_{SUCYC}
t_{RISE}	SSCK clock rising time	Master		–	–	1	t_{CYC}(2)
		Slave		–	–	1	µs
t_{FALL}	SSCK clock falling time	Master		–	–	1	t_{CYC}(2)
		Slave		–	–	1	µs
t_{SU}	SSO, SSI data input setup time			100	–	–	ns
t_H	SSO, SSI data input hold time			1	–	–	t_{CYC}(2)
t_{LEAD}	$\overline{SCS}$ setup time	Slave		$1t_{CYC} + 50$	–	–	ns
t_{LAG}	$\overline{SCS}$ hold time	Slave		$1t_{CYC} + 50$	–	–	ns
t_{OD}	SSO, SSI data output delay time			–	–	1	t_{CYC}(2)
t_{SA}	SSI slave access time		$2.7\ \text{V} \le V_{CC} \le 5.5\ \text{V}$	–	–	$1.5t_{CYC} + 100$	ns
			$2.2\ \text{V} \le V_{CC} < 2.7\ \text{V}$	–	–	$1.5t_{CYC} + 200$	ns
t_{OR}	SSI slave out open time		$2.7\ \text{V} \le V_{CC} \le 5.5\ \text{V}$	–	–	$1.5t_{CYC} + 100$	ns
			$2.2\ \text{V} \le V_{CC} < 2.7\ \text{V}$	–	–	$1.5t_{CYC} + 200$	ns

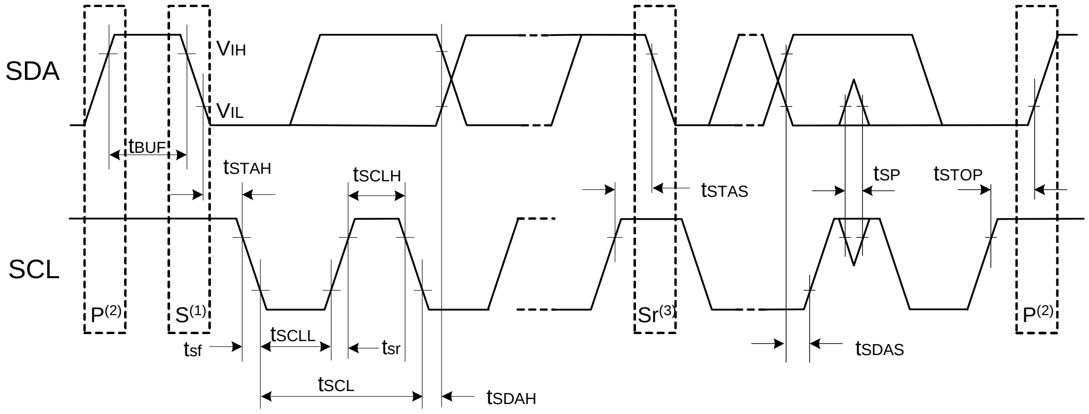
NOTES:

1. V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. $1t_{CYC} = 1/f1(s)$

Table 5.15 Timing Requirements of I^2C bus Interface (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t_{SCL}	SCL input cycle time		$12t_{CYC} + 600$(2)	–	–	ns
t_{SCLH}	SCL input “H” width		$3t_{CYC} + 300$(2)	–	–	ns
t_{SCLL}	SCL input “L” width		$5t_{CYC} + 500$(2)	–	–	ns
t_{sf}	SCL, SDA input fall time		–	–	300	ns
t_{SP}	SCL, SDA input spike pulse rejection time		–	–	$1t_{CYC}$(2)	ns
t_{BUF}	SDA input bus-free time		$5t_{CYC}$(2)	–	–	ns
t_{STAH}	Start condition input hold time		$3t_{CYC}$(2)	–	–	ns
t_{STAS}	Retransmit start condition input setup time		$3t_{CYC}$(2)	–	–	ns
t_{STOP}	Stop condition input setup time		$3t_{CYC}$(2)	–	–	ns
t_{SDAS}	Data input setup time		$1t_{CYC} + 20$(2)	–	–	ns
t_{SDAH}	Data input hold time		0	–	–	ns

NOTES:
1. V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V and T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. $1t_{CYC} = 1/f1(s)$



NOTES:
1. Start condition
2. Stop condition
3. Retransmit start condition

Figure 5.7 I/O Timing of I^2C bus Interface

Table 5.17 Electrical Characteristics (2) [Vcc = 5 V]
(Topr = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	12	20	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	10	16	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	7	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	5.5	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4.5	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	6	12	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.5	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1	–	150	400	µA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz FMR47 = 1	–	150	400	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz Program operation on RAM Flash memory off, FMSTP = 1	–	35	–	µA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	30	90	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	18	55	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (high drive) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	3.5	–	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (low drive) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	2.3	–	µA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	0.7	3.0	µA
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	1.7	–	µA

Timing Requirements
(Unless Otherwise Specified: V_{CC} = 5 V, V_{SS} = 0 V at T_{opr} = 25°C) [V_{CC} = 5 V]

Table 5.18 XIN Input, XCIN Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	50	–	ns
$t_{WH(XIN)}$	XIN input “H” width	25	–	ns
$t_{WL(XIN)}$	XIN input “L” width	25	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

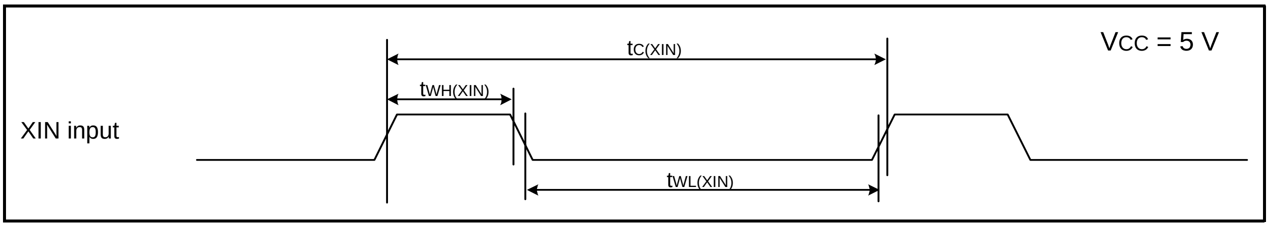


Figure 5.8 XIN Input and XCIN Input Timing Diagram when V_{CC} = 5 V

Table 5.19 TRAIO Input, $\overline{\text{INT1}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	100	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	40	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	40	–	ns

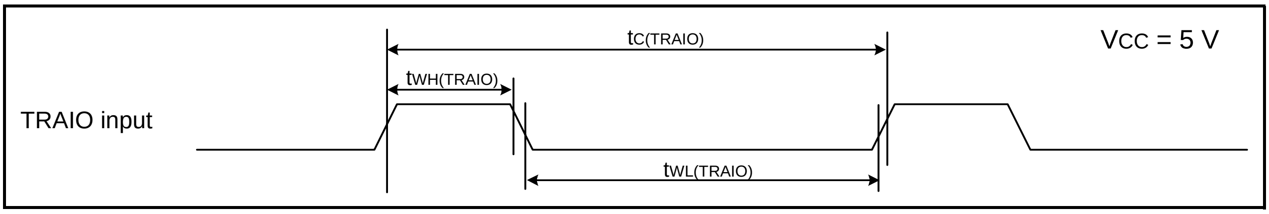


Figure 5.9 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when V_{CC} = 5 V

Table 5.20 TRFI Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	400(1)	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	200(2)	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	200(2)	–	ns

NOTES:
1. When using timer RF input capture mode, adjust the cycle time to (1/timer RF count source frequency × 3) or above.
2. When using timer RF input capture mode, adjust the pulse width to (1/timer RF count source frequency × 1.5) or above.

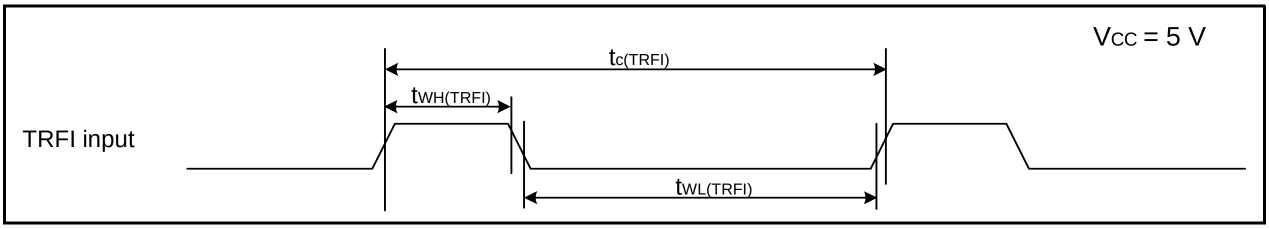


Figure 5.10 TRFI Input Timing Diagram when V_{CC} = 5 V

Timing requirements
(Unless Otherwise Specified: V_{CC} = 3 V, V_{SS} = 0 V at Topr = 25°C) [V_{CC} = 3 V]

Table 5.25 XIN Input, XCIN Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input “H” width	40	–	ns
$t_{WL(XIN)}$	XIN input “L” width	40	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	µs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	µs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	µs

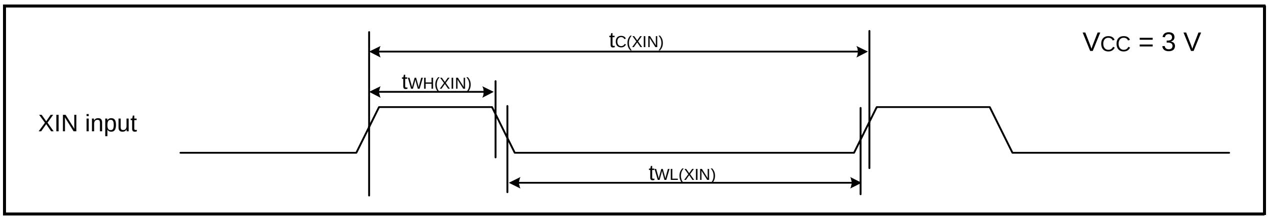


Figure 5.13 XIN Input and XCIN Input Timing Diagram when V_{CC} = 3 V

Table 5.26 TRAIO Input, $\overline{\text{INT1}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	120	–	ns

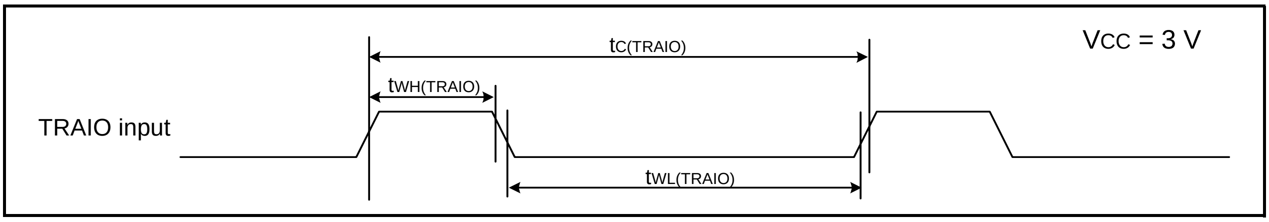


Figure 5.14 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when V_{CC} = 3 V

Table 5.27 TRFI Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	1200(1)	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	600(2)	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	600(2)	–	ns

NOTES:
1. When using timer RF input capture mode, adjust the cycle time to (1/timer RF count source frequency × 3) or above.
2. When using timer RF input capture mode, adjust the pulse width to (1/timer RF count source frequency × 1.5) or above.

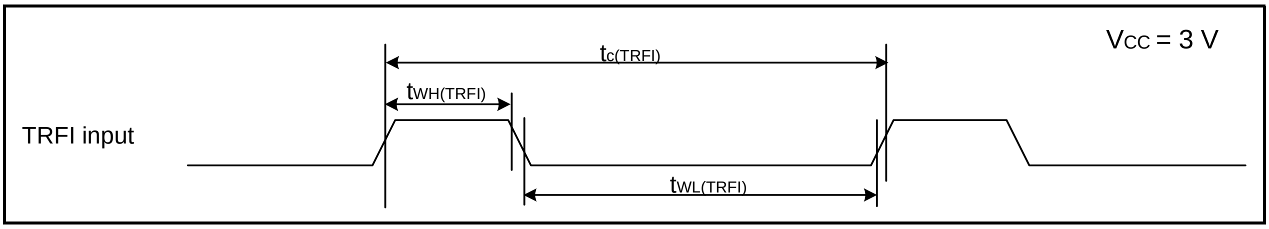


Figure 5.15 TRFI Input Timing Diagram when V_{CC} = 3 V

Table 5.35 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	–	ns
$t_{W(CKH)}$	CLKi input “H” width	400	–	ns
$t_{W(CKL)}$	CLKi input “L” width	400	–	ns
$t_{d(C-Q)}$	TXDi output delay time	–	200	ns
$t_{h(C-Q)}$	TXDi hold time	0	–	ns
$t_{su(D-C)}$	RXDi input setup time	150	–	ns
$t_{h(C-D)}$	RXDi input hold time	90	–	ns

i = 0 to 2

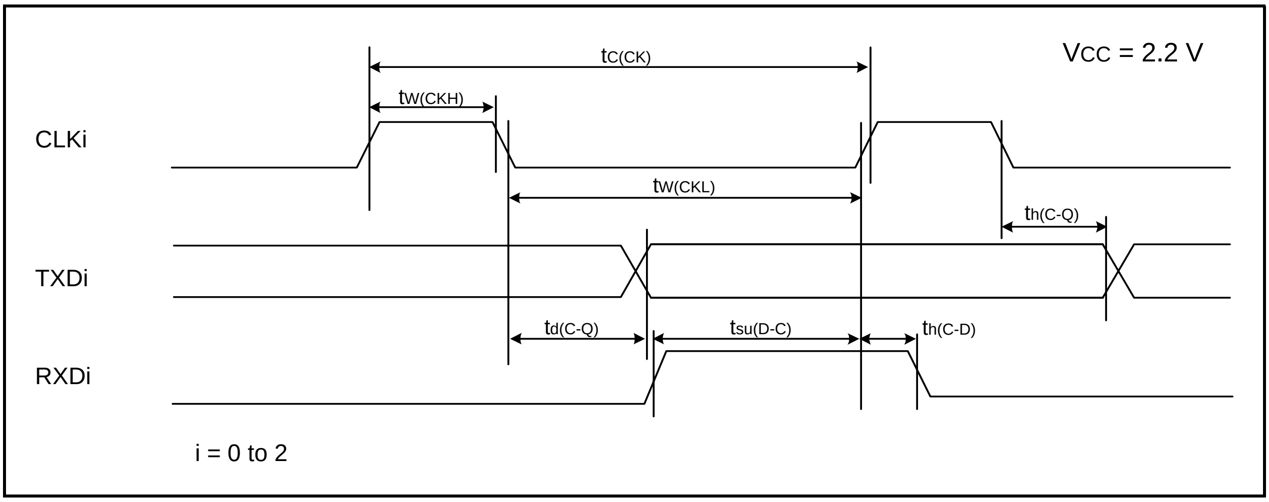


Figure 5.21 Serial Interface Timing Diagram when V_{CC} = 2.2 V

Table 5.36 External Interrupt $\overline{\text{INTi}}$ (i = 0, 2, 3) Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{W(INH)}$	$\overline{\text{INT0}}$ input “H” width	1000[1]	–	ns
$t_{W(INL)}$	$\overline{\text{INT0}}$ input “L” width	1000[2]	–	ns

NOTES:

1. When selecting the digital filter by the $\overline{\text{INTi}}$ input filter select bit, use an $\overline{\text{INTi}}$ input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{\text{INTi}}$ input filter select bit, use an $\overline{\text{INTi}}$ input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

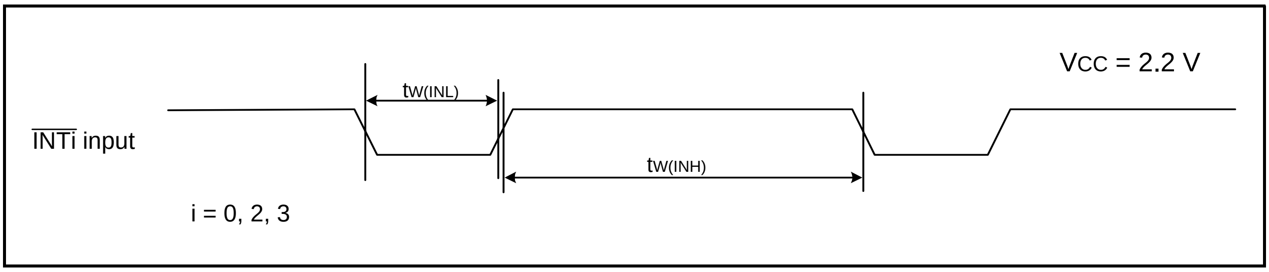
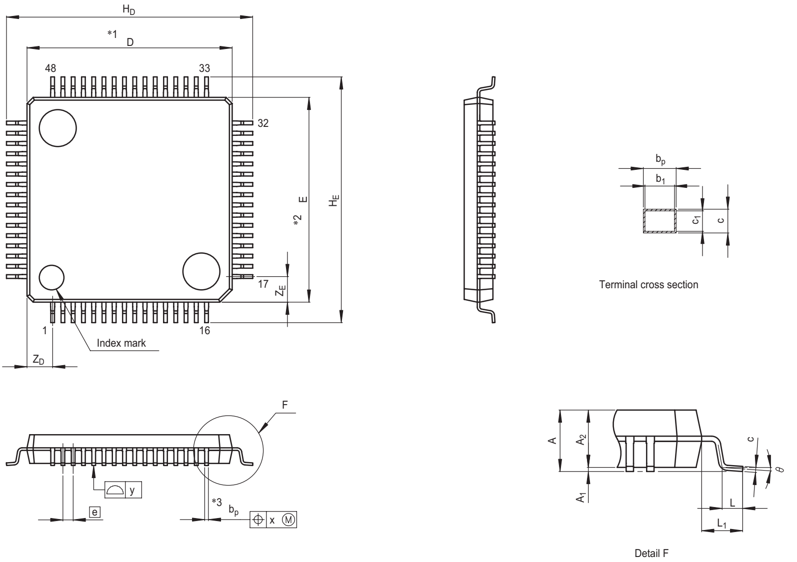


Figure 5.22 External Interrupt $\overline{\text{INTi}}$ Input Timing Diagram when V_{CC} = 2.2 V

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.

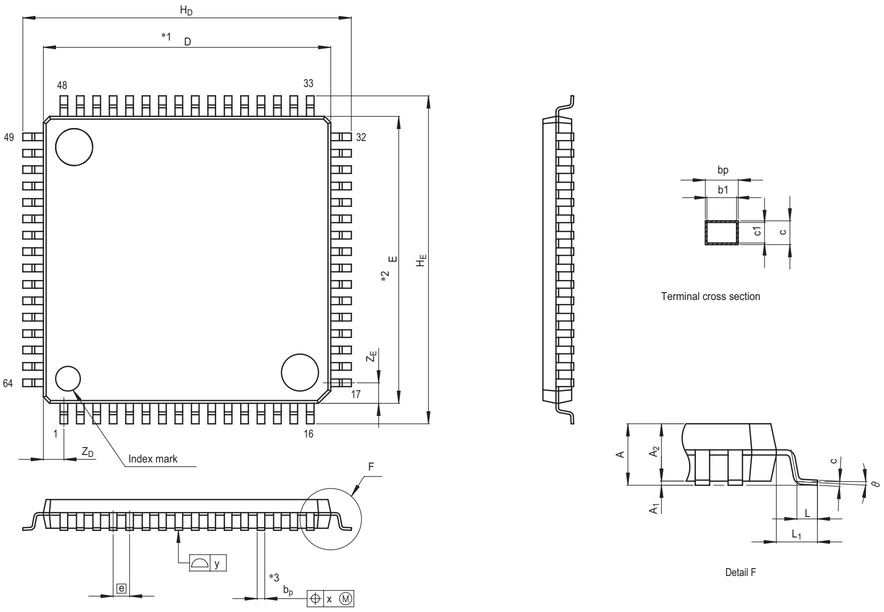
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-10x10-0.50	PLQP0064KB-A	64P6Q-A / FP-64K / FP-64KV	0.3g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
$\boxed{e}$	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.35	0.5	0.65
L_1	—	1.0	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A	0.7g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
$\boxed{e}$	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

REVISION HISTORY	R8C/2A Group, R8C/2B Group Datasheet

Rev.	Date	Description	
		Page	Summary
2.00	Oct 17, 2007	33	Table 5.1; Pd: Rated Value “TBD” → “700” revised, “NOTE1” added
		59	Package Dimensions “PTLG0064JA-A (64F0G) package” added
2.10	Nov 26, 2007	2, 4	Table 1.1, Table 1.3 Clock: “Real-time clock (timer RE)” added
		6, 7	Table 1.5 and Figure 1.1 revised
		8, 9	Table 1.6 and Figure 1.2 revised
		20, 21	Figure 3.1 and Figure 3.2 revised
		22	Table 4.1 002Ch: High-Speed On-Chip Oscillator Control Register 7 added
		35	Table 5.2 NOTE2 revised
		41	Table 5.11 revised